SOLDER SPHERE INSTALLATION
There are different methods of installation currently available.

Solder spheres can be supplied in accordance with the current ANSI/EIA-481 standard compliant tape-and-reel format to work seamlessly with existing SMT equipment.

An alternative to tape-and-reel is to use a bulk feeder with your SMT equipment. This solution is less expensive than tape-and-reel.

RELIABILITY TESTING
The DC resistance across each individual solder sphere joint has been extensively tested, meeting stringent XGR Technologies requirements across the following methods and standards:
- Mechanical Shock (EIA-481 standard)
- Bump (IEC 60068-2-29)
- Vibration (IEC 60068-2-64)
- Thermal Shock (MIL-STD-883CA)
- Dry Heat Aging
- Moist Heat Aging

![Image of solder spheres](image)

RELATIVE SHIELDING EFFECTIVENESS VS. METAL CANS
The shielding effectiveness of XGR™ SnapShot® EMI Shields have also been evaluated in side-by-side testing with soldered metal cans, with positive results.

At cellular and ultra high frequencies, testing shows that the performance of XGR™ SnapShot EMI Shields exceeds that of many commonly used cans with perforated holes or snap-on lids.

RELATIVE SHIELDING EFFECTIVENESS OF XGR SNAPSHOT EMI SHIELDS VERSUS TRADITIONAL METAL CANS (10 dB per Division)

![Graph of shielding effectiveness](image)